Nadcap
Administered by PRI

SCOPE OF ACCREDITATION

Electronics - Printed Boards

TTM Technologies Inc-Stafford Division
4 Old Monson Rd
Stafford, CT 06075

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7119 Rev I - Nadcap Audit Criteria for Electronics Printed Boards (to be used on audits BEFORE 30-Jul-2023)

03–Company Information (mandatory)
04–General Information (mandatory)
05–Process Control (mandatory)
06– Engineering Source File Processing (mandatory)
07.1– Material Control: General (mandatory)
07.2– Material Control: PrePreg
08.1– Imaging – Photoprocess (mandatory)
08.2.1– DES – Developing Photoimageable Resist (mandatory
08.2.2– DES – Copper Etching of Inner Layers and Outer Layers (mandatory)
08.2.3– DES – Stripping of Resist Film and Etch–Resist Plating (mandatory)
08.2– Imaging – Develop–Etch–Strip (DES) and Strip–Etch–Strip (SES) (mandatory)
08.3– Etched Image Inspection (Manual or AOI) (mandatory)
09.1– Permanent Solder Mask: Solder Mask Application
09.2– Permanent Solder Mask: Solder Mask Exposing
09.3– Permanent Solder Mask: Solder Mask Develop and Cure
10– Oxide Coating / Oxide Replacement Coating
11– Material Lay–Up and Lamination (mandatory)
12.1– Drilling: Mechanical Drilling
12.3– Drilling: Laser Drilling – Out Sourced
12.4– Drilling: Post–Drill Cleaning and Etchback
13.1– Epoxy Hole Fill and Planarization: Non–Conductive and/or Conductive Epoxy Hole Fill
13.2– Epoxy Hole Fill and Planarization: Planarization
14.1– Copper Plating: Electroless Copper/Direct Metallization (mandatory)
14.2– Copper Plating: Electroplated Copper (mandatory)
15.1– Final Finishes: Hot Air Solder Leveling (HASL)

15.2– Final Finishes: Fused Tin–Lead
15.3– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish
15.4– Final Finishes: Electroplated Final Finish
15.6– Final Finishes: Wire Bondable Plating
16– Legend and Marking
17– Routing and Machining
18– Electrical Test – Functional (mandatory)
19– X–Ray Fluorescence (XRF)
20– Microsection Sample Selection Preparation and Inspection (mandatory)
21– Structural Integrity (mandatory)
22– Materials Lab (mandatory)
23– Chemistry Lab (mandatory)
24– Monthly Quality Conformance Testing
25– Final Validation (mandatory
26– Packaging (mandatory)

AC7119S Rev NA - Nadcap Supplemental Audit Criteria for Printed Boards (to be used on/AFTER 10-Jul-2022)
S-U1 Honeywell

AC7119/2 Rev B - Nadcap Audit Criteria for Electronics Flexible and Rigid-Flexible Printed Boards (to be used on audits on/after 11 March 2018)
04– Handling
05– Material
06– Cover Material Application
07– Post–Drill Cleaning and Etchback
08– Stiffener Bonding
09– Strain Relief
10– Testing
11– Depanelization
12– Packaging
13– Final Validation

AC7119/5 - Nadcap Audit Criteria for Electronics High Frequency (MICROWAVE) Printed Boards